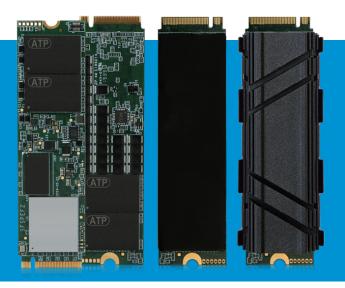


M.2 NVMe

Targeted Product Portfolio, Engineered Specifically for Your Mission Critical Applications



Key Features

- MCU-based Power Loss Protection Design *
- Self-Encrypting Drive (SED) with AES 256-bit Encryption, TCG OPAL 2.0*
- Thermal Management Solutions**
- End-to-End Data protection
- TRIM function support
- * May vary by product and project support
- ** Customization available on a project basis.

M.2 solid state modules based on the NVMe™protocol leverage the blazing-fast PCI Express® (PCle®) interface to deliver dramatic improvements in speed and performance to fulfill the increasing demand for responsiveness in enterprise storage systems and to support the growing data-hungry needs of today's enterprise. Delivering 32 Gb/s bandwidth on a PCle 3.1 x4 slot (8 Gb/s per lane), ATP NVMe SSDs outperform Serial ATA 6 Gb/s SSDs with 4-6X faster access, over 3X lower latency, and higher Input/Output per Second (IOPS). ATP NVMe SSDs with industrial operating temperature rating deliver stable performance even in extreme temperatures ranging from -40°C to 85°C, while Dynamic Thermal Throttling automatically adjusts the speed to maintain cooler operation under intense and heavy workloads.

Adopting NVMe 1.3 specifications and integrating 3D NAND TLC technology, ATP's M.2 2280 NVMe modules offer up to 1.92TB of storage capacity and deliver boosted performance with sequential read up to 3,420 MB/s, sequential write up to 3,050 MB/s, and random read/write IOPS up to 225,200/179,200.

Designed to move past the limitations of mechanical drives, NVMe was specifically built from the ground up for faster, more efficient access to storage devices with non-volatile memory such as current NAND flash solutions and future non-volatile memory technologies. These SSDs can deliver fast, reliable and durable performance for any demanding application.

Specifications

M.2 NVMe							
Product Line		nium	Superior				
Product Line	N750Pi	N700Pi	N650Si	N650Sc			
Interface		PCIe G	G3 x4				
Flash Type	3D TLC (pSLC mode) 3D TLC						
Form Factor		M.2 228	30-D2-M				
Operating Temperature (Tcase) ¹	-40°C	°C to 85°C -40°C to 85°C 0°C to 70					
Power Loss Protection Options	Hardware + F	irmware Based	Hardware + Firmware Based or Firmware Based				
Optional SED Features		AES 256-bit Encry	S 256-bit Encryption, TCG Opal 2.0				
Capacity	40 GB to 320 GB	40 GB to 640 GB	120 GB to 960 GB				
Performance							
Sequential Read (MB/s) up to	3,1	50	3,420				
Sequential Write (MB/s) up to	2,670	2,820	3,050				
Random Reads IOPS up to	147,789	(4K, QD32)	222,700 (4K, QD32)				
Random Writes IOPS up to	114,227	7 (4K, QD32) 176,600 (4K, QD32)					
	Endu	rance and Reliability					
Endurance (TBW) ² up to	16,000 TB	21,300 TB	4,640 TB				
Reliability MTBF @ 25°C		>2,000,0	000,000 hours				
		Others					
Dimensions: L x W x H (mm)	80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink)						
Certifications	CE, FCC, BSMI, UKCA, RoHS, REACH						
Warranty	5	years	2 years				

M.2 NVMe						
Product Line	Superior					
Product Line	N600Si	N600Sc				
Interface	PCIe G3 x4					
Flash Type	3D TLC					
Form Factor	M.2 2280-D2-M					
Operating Temperature (Tcase) ¹	-40°C to 85°C	0°C to 70°C				
Power Loss Protection Options	Hardware + Firmware Based or Firmware Base					
Optional SED Features	AES 256-bit Encryption, TCG Opal 2.0					
Capacity	120 GB to 1,920 GB					
	Performance					
Sequential Read (MB/s) up to	3,420					
Sequential Write (MB/s) up to	3,050					
Random Reads IOPS up to	225,200 (4K, QD32)					
Random Writes IOPS up to	179,200 (4K, QD32)					
	Endurance and Reliability					
Endurance (TBW) ² up to	5,585 TB					
Reliability MTBF @ 25°C	ability MTBF @ 25°C >2,000,000 hours					
Others						
Dimensions: L x W x H (mm)		80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink)				
Certifications	CE, FCC, BSMI, UKC	CA, RoHS, REACH				
Warranty	2 years					

¹ Case Temperature, the composite temperature as indicated by SMART temperature attributes. 2 Under highest Sequential write value. May vary by density, configuration and applications.

Technologies & Add-On Services	S.M.A.R.T.	Hardware-based Power Loss Protection	AutoRefresh	Advanced Wear Leveling	Dynamic Data Refresh	End-to End Data Protection	Secure Erase	P TCG Opal 2.0	Industrial Temperature	Anti-Sulfur Resistors	Conformal Coating
Premium	0	0	0	0	0	0	A	0	0	A	A
Superior	0	0	0	0	0	0	A	0	A	A	A

 $[\]blacktriangle$: Customization option available on a project basis.

Hot Items Ordering Information							
Product Line	Capacity ₁	Operating Temperature ₂	Power Loss Protection ₃	SED ₄	P/N		
N600Si	120GB	-40°C to 85°C	Hardware + Firmware Based	-	AF120GSTJA-8BAIP		
N600Si	240GB	-40°C to 85°C	Hardware + Firmware Based	-	AF240GSTJA-8BAIP		
N600Si	480GB	-40°C to 85°C	Hardware + Firmware Based	-	AF480GSTJA-8BAIP		
N600Si	960GB	-40°C to 85°C	Hardware + Firmware Based	-	AF960GSTJA-8BAIP		
N600Si	1920GB	-40°C to 85°C	Hardware + Firmware Based	-	AF1T92STJA-8BAIP		
N600Si	120GB	-40°C to 85°C	Firmware Based	-	AF120GSTJA-8BAIX		
N600Si	240GB	-40°C to 85°C	Firmware Based	-	AF240GSTJA-8BAIX		
N600Si	480GB	-40°C to 85°C	Firmware Based	-	AF480GSTJA-8BAIX		
N600Si	960GB	-40°C to 85°C	Firmware Based	-	AF960GSTJA-8BAIX		
N600Si	1920GB	-40°C to 85°C	Firmware Based	-	AF1T92STJA-8BAIX		
N600Sc	120GB	0°C to 70°C	Hardware + Firmware Based	-	AF120GSTJA-8BAXP		
N600Sc	240GB	0°C to 70°C	Hardware + Firmware Based	-	AF240GSTJA-8BAXP		
N600Sc	480GB	0°C to 70°C	Hardware + Firmware Based	-	AF480GSTJA-8BAXP		
N600Sc	960GB	0°C to 70°C	Hardware + Firmware Based	-	AF960GSTJA-8BAXP		
N600Sc	1920GB	0°C to 70°C	Hardware + Firmware Based	-	AF1T92STJA-8BAXP		
N600Sc	120GB	0°C to 70°C	Firmware Based	-	AF120GSTJA-8BAXX		
N600Sc	240GB	0°C to 70°C	Firmware Based	-	AF240GSTJA-8BAXX		
N600Sc	480GB	0°C to 70°C	Firmware Based	-	AF480GSTJA-8BAXX		
N600Sc	960GB	0°C to 70°C	Firmware Based	-	AF960GSTJA-8BAXX		
N600Sc	1920GB	0°C to 70°C	Firmware Based	-	AF1T92STJA-8BAXX		

¹ Amount of actual usable storage that can be utilize.

Product spec and its related information are subject to change without advance notice. Please refer to <u>www.atpinc.com</u> for latest information

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² Refers to Case Temperature range during device operation, as indicated by SMART temperature attributes.

3 Hardware + Firmware based power loss protection design with Level 4 (data-in-flight) protection; Firmware based power loss protection design with Level 1 (data-at-rest) protection.

4 Allows data written to and read from the SSD to be constantly and automatically encrypted and decrypted. Conforms to TCG Opal 2.0 and uses AES 256-bit HW encryption.